

**Remarks**

Claims 1-9 remain in the application.

The Abstract of the Disclosure has been amended to eliminate reference numbers.

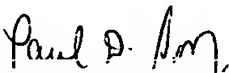
Consideration and allowance of the claims is respectfully requested.

Attached hereto is a marked up version of the changes made to the specification by the current amendment. The attached page is captioned "Version With Markings to Show Changes Made."

Respectfully submitted,

Date

2-11-02



Paul D. Greeley  
Attorney for Applicant(s)  
Registration No. 31,019  
Ohlandt, Greeley, Ruggiero & Perle, L.L.P.  
One Landmark Square, 10<sup>th</sup> Floor  
Stamford, CT 06901-2682  
(203) 327-4500

10074202.021202  
2021202.021202

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**In The Abstract of the Disclosure**

Please amend the Abstract of the Disclosure as follows:

A blade-like connecting needle for measuring a semiconductor wafer has an increased capability for measuring a small current and also has stable characteristics. The blade-like connecting needle [1] includes a blade signal [10] line for transmitting signal from the semiconductor wafer, a support insulator [8] covering at least a portion of the blade signal line [10], a plurality of blade guard patterns [12a, 12b, 12c, 12d] disposed in or on the support insulator [8] for electromagnetically shielding the blade signal line [10], and a probe [2] supported on the support insulator [8] and connected to the blade signal line [10]. There are also disclosed processes of producing the blade-like connecting needle [1]. A method for manufacturing a coaxial or hollow blade-like connecting needle is also provided.

2021-02-20 10:40:00